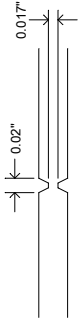


REVISION HISTORY				
ECO	REV	DESCRIPTION	APPROVED	DATE
-	1	1ST PROTOTYPE	KEITH B.	08-16-10

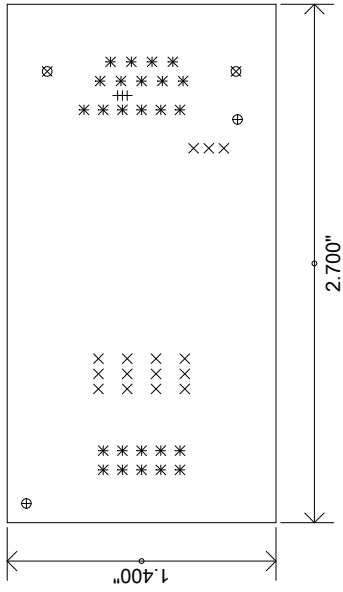
NOTES: UNLESS OTHERWISE SPECIFIED

- FAB PER IPC-A-600
-EPOXY FIBERGLASS, NEMA GRADE FR-4
-FINISHED THICKNESS TO BE 0.062" +/- .005"
-TOTAL OF 4 LAYERS WITH 1 OZ. CU ON THE OUTER LAYERS AND 1 OZ. CU ON THE INNER LAYERS
-FLAMMABILITY RATING: 94V-0 MINIMUM
- SIZE: CUT TO DIMENSIONS AND TOLERANCES SHOWN
-DRILL HOLES PER SCHEDULE. PLATE THROUGH HOLES WITH COPPER, 0.001" THICK MIN.
-ALL HOLE SIZES ARE SPECIFIED AFTER PLATING
-HOLE LOCATION TOLERANCES ARE +/- 0.003" IN RELATION TO CENTER
-SMOBC USING LPI BOTH SIDES, COLOR GREEN
-GOLD IMMERSION BOTH SIDES
-FOR SILKSCREEN: LEAD FREE SOLDER MAY BE USED FOR PROTOTYPE)
-LEAD FREE SOLDER MAY BE USED FOR PROTOTYPE)
-DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE.
PAD SIZE MAY BE MODIFIED TO MEET END FINISH.
- PCBs ARE TO BE ROHS COMPLIANT
DESIGN HAS SOLDER MASK DEFINED PADS ON U1.
- SOLDER MASK SIZE IS 25 MIL AND PAD SIZE IS 29 MIL.
DO NOT CHANGE ANY SIZE ON THIS COMPONENT.
- SCORING FOR PANELIZED PCB:

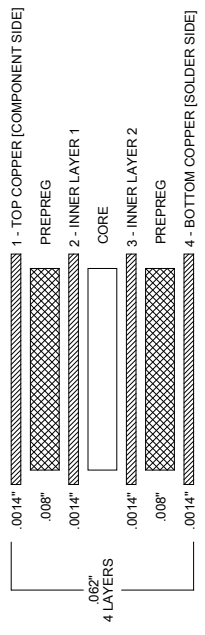


SIZE	QTY	SYM	PLATED	TOL
0.010"	3	+	YES	+/-0.003"
0.032"	15	X	YES	+/-0.003"
0.040"	25	*	YES	+/-0.003"
0.070"	2	⊕	NO	+/-0.003"
0.120"	2	⊗	NO	+/-0.003"

SHOWN FROM COMPONENT SIDE



LAYER STRUCTURE



UNLESS OTHERWISE SPECIFIED

DIMENSIONS ARE IN INCHES
TOLERANCES:
0.XX" = +/- 0.01"
0.XXX" = +/- 0.005"
INTERPRET DIM AND TOL PER
ASME Y14.5M-1994

THIRD ANGLE PROJECTION

APPROVALS	
PCB DES.	KEITH B.
APP ENG.	KEITH B.
SCALE = 1:1	

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LINEAR
TECHNOLOGY

TITLE: SCHEMATIC
RS485/RS422 uMODULE ISOLATOR, LOW EMI

SIZE: N/A
IC NO.: LTM2881CY-3/-5
REV. DEMO CIRCUIT 1746A

DATE: Tuesday August 16, 2010
SHEET 1 OF 1

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